



## DESCRIPTION

Lingsen' SIP is a substrate based, with surface mount process., with encapsulated lid package. It is available in pin count is 16 or can be customized to individual customer needs.

## APPLICATIONS

- Module

## FEATURES

- Pin count range is 16.
- Lead pitch of 2 mm.

## SPECIFICATIONS

Substrate: FR4

Solder SAC305

Packing: 150DegC PPE tray

## PACKAGE AVAILABILITY

Package Size (mm)	Lead Pitch (mm)	Lead Count
8 x 13	2	16

## RELIABILITY

MSL	60°C/60%RH 168h + IR*3times
Thermal shock	-40degC<->85degC(each 30minutes), 200cycle
High temperature storage	95degC,1000hrs
Low temperature storage	-40degC,1000hrs
Damp heat storage	85degC,85%RH,1000hrs

## CROSS-SECTION

